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ney Docket No. 021653-012900US

U.S. DEPARTMENT OF COMMERCE
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2006 AUG -7 PM 3: 08

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents of the new address(es) below

FINANCE SECTION

1. Name of conveying party(ies)

Ting Cheong Ang

2. Name and address of receiving party(ies)

Semiconductor Manufacturing

Name: International (Shanghai) Corporation

Internal Address: _____

Additional name(s) of conveying party(ies) attached? Yes No

Street Address: 18 Zhang Jiang Rd.,
Pudong New Area

City: Shanghai

State: _____

Country: People's Republic of China Zip: 201203

3. Nature of conveyance/Execution Date(s):

Execution Date(s) 06/30/06

- Assignment Merger
- Security Agreement Change of Name
- Joint Research Agreement
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other _____

Additional name(s) & address(es) attached? Yes No

4. Application or patent number(s):

This document is being filed together with a new application.

A. Patent Application No.(s)
11/418,501

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Daniel Mao

Internal Address: _____

TOWNSEND AND TOWNSEND AND CREW LLP

Street Address: Two Embarcadero Center,
Eighth Floor

City: San Francisco

State: California Zip: 94111-3834

Phone Number: (415) 576-0200

Fax Number: (415) 576-0300

Email Address: DMao@townsend.com

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- Authorized to be charged by credit card
- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 numbers _____
Expiration Date _____

b. Deposit Account Number 20-1430

Authorized User Name Townsend and
Townsend and Crew LLP

9. Signature:

Daniel Mao

Signature

August 4, 2006
Date

Daniel Mao

Name of Person Signing Atty. Reg. No. 51,995

Total number of pages including cover sheet, attachments, and documents:

2

Attorney Docket No.: 021653-012900US
 Client Reference No.: I-03-226

ASSIGNMENT OF PATENT APPLICATION

SOLE

WHEREAS, Ting Cheong Ang of No. 18 Wenchang Road, Beijing Economic Technology Development Area, Beijing, 100176 People's Republic of China, hereinafter referred to as "Assignor," is the inventor of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: METHOD FOR FORMING LOW DIELECTRIC
 CONSTANT FLUORINE-DOPED LAYERS

Filing Date: May 3, 2006

Application No.: 11/418,501; and

WHEREAS, Semiconductor Manufacturing International (Shanghai) Corporation, a corporation of People's Republic of China, located at 18 Zhang Jiang Rd., Pudong New Area, Shanghai, 201203, People's Republic of China, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has assigned, and by these presents does assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on any patent application claiming priority from the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignor had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees that Assignor will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has signed his/her name on the date indicated.

Dated: 30 - June - 2006

Ting Cheong Ang
 Ting Cheong Ang

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PATENT

RECORDED: 08/07/2006

REEL: 018157 FRAME: 0373